

Title (en)

MULTI-LAYER STAMPED ELECTRICALLY CONDUCTIVE CIRCUIT AND METHOD FOR MAKING SAME

Title (de)

MEHRSCHICHTIGE GEPRÄGTE ELEKTRISCH LEITFÄHIGE SCHALTUNG UND VERFAHREN ZU DEREN HERSTELLUNG

Title (fr)

CIRCUIT ELECTRIQUEMENT CONDUCTEUR EMBOUTI MULTICOUCHE ET PROCEDE DE FABRICATION ASSOCIE

Publication

EP 0908077 A1 19990414 (EN)

Application

EP 97918271 A 19970501

Priority

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- US 64272496 A 19960503

Abstract (en)

[origin: WO9742800A1] A method of making a multi-layer electronic circuit and the circuit made thereby, wherein the method comprises making each of at least two interconnected circuit layers by applying a layer of conductive material (34, 36) on a layer (38) of insulative material using a stamping die which defines a selected pattern in the conductive layer (34, 36), aligning and laminating the circuit layers to a substrate (32), and interconnecting the layers of the conductive material (34, 36) at selected locations. Apertures (40, 42, 44) are defined at selected locations in the insulative material for a subsequent electrical interconnection. These apertures (40, 42, 44) may be defined by stamping them into the insulative material simultaneously with the application of the patterned conductive material on the insulative material.

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